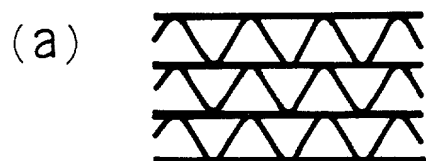


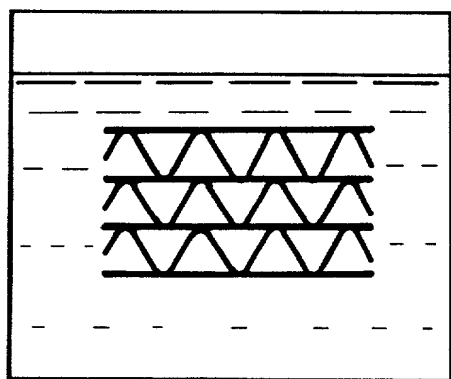
FIG. 1



corrugated cardboard



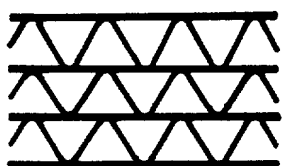
(b)



Dipping into the mixed slurry of
phenolic resin and Si powder



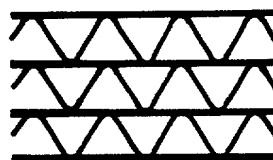
(c)



Drying at 70°C



(d)

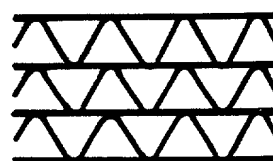


(Si powder + C)

Pyrolysis at 1000°C in Ar



(e)

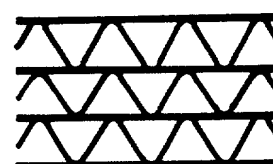


(SiC + pore + C)

Reaction-bonding & melt infiltration
at 1450°C for 1 h in vacuum



(f)



(SiC/Si)

SiC/Si composites with
corrugated cardboard
structure